

SOT1058-1

plastic low profile fine-pitch ball grid array package; 136 balls

11 October 2018

Package information

1 Package summary

| | |
|---------------------------------------|--|
| Terminal position code | B (bottom) |
| Package type descriptive code | LFBGA136 |
| Package type industry code | LFBGA136 |
| Package style descriptive code | LFBGA (low profile fine-pitch ball grid array) |
| Package body material type | P (plastic) |
| Mounting method type | S (surface mount) |
| Issue date | 03-01-2008 |
| Manufacturer package code | SOT1058 |

Table 1. Package summary

| Parameter | Min | Nom | Max | Unit |
|--------------------------------|------|------|------|------|
| package length | 9.9 | 10 | 10.1 | mm |
| package width | 9.9 | 10 | 10.1 | mm |
| seated height | - | - | 1.45 | mm |
| package height | 0.95 | 1.03 | 1.1 | mm |
| nominal pitch | - | 0.65 | - | mm |
| actual quantity of termination | - | 136 | - | |



2 Package outline

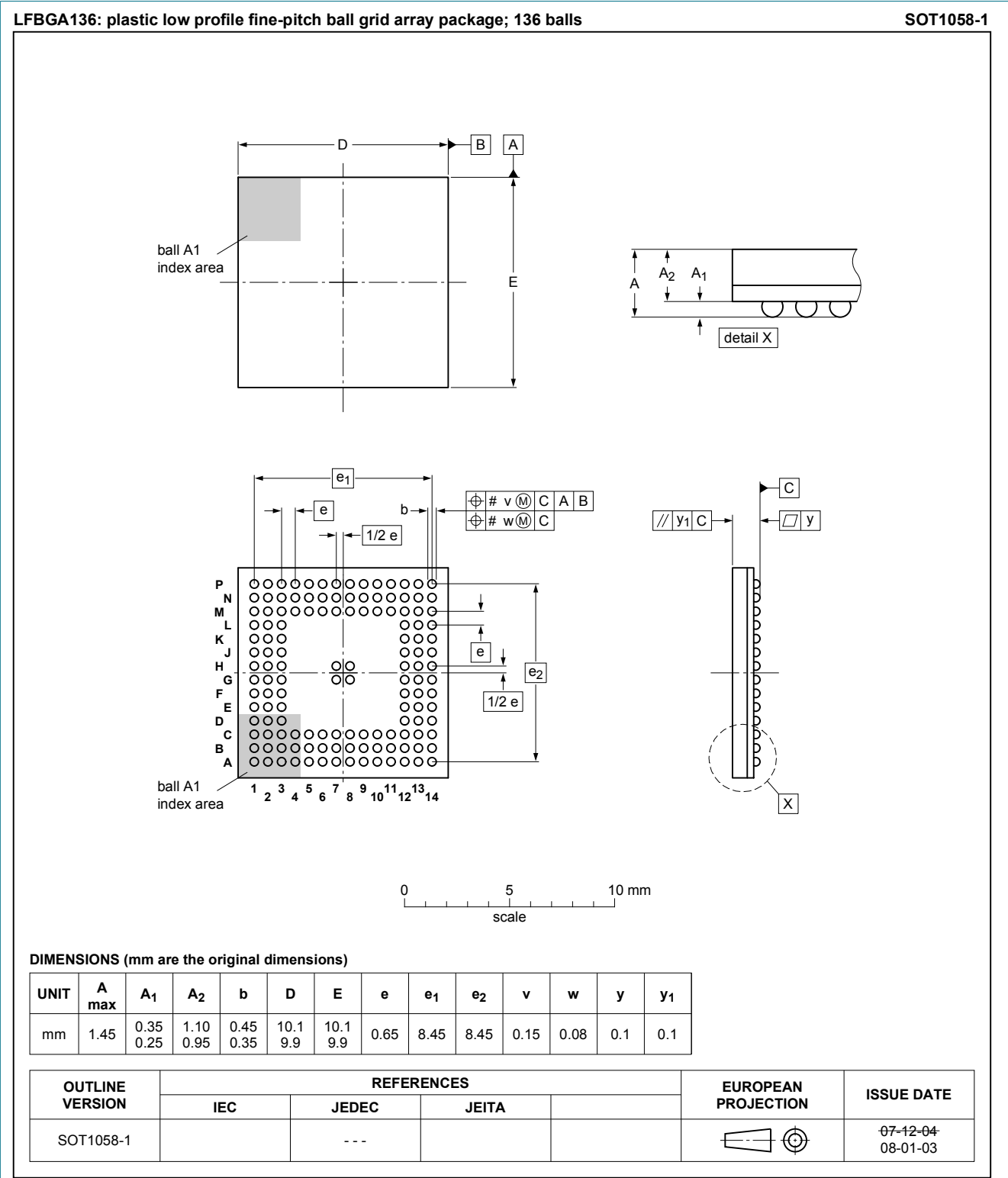


Figure 1. Package outline LFBGA136 (SOT1058-1)

3 Legal information

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